

Application No. 10/014,679
Response After Final "B" Under 37 C.F.R. § 1.111 dated September 9, 2004
Reply to FINAL Office Action mailed June 9, 2004

Response Under 37 C.F.R. § 1.116
Expedited Procedure
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AMENDMENTS TO THE CLAIMS

The listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. **(Original)** An integrated optical device comprising:
a vertically lasing semiconductor optical amplifier (VLSOA) comprising:
an amplifier input;
an amplifier output;
a semiconductor active region;
an amplifying path connecting the amplifier input to the amplifier output and
traversing the semiconductor active region; and
a vertical laser cavity including the semiconductor active region; and
an optical element, wherein a portion of the VLSOA and a portion of the optical element
are formed on a common substrate by a common fabrication process and at least one parameter
varies between the portion of the VLSOA and the portion of the optical element.
2. **(Original)** The integrated optical device of claim 1 wherein:
the portion of the VLSOA and the portion of the optical element have different transition
energies; and
the difference in transition energies between the portion of the VLSOA and the portion of
the optical element is a result of the selective area epitaxy.
3. **(Original)** The integrated optical device of claim 1 wherein:
the portion of the VLSOA and the portion of the optical element have different transition
energies; and
the difference in transition energies between the portion of the VLSOA and the portion of
the optical element is a result of impurity induced disordering.

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4. **(Original)** The integrated optical device of claim 1 wherein:
 the portion of the VLSEA and the portion of the optical element have different transition energies; and
 the difference in transition energies between the portion of the VLSEA and the portion of the optical element is a result of stress-induced disordering.
5. **(Original)** The integrated optical device of claim 1 wherein the optical element includes a passive optical waveguide.
6. **(Original)** The integrated optical device of claim 5 wherein:
 the passive optical waveguide includes a core; and
 the core and the active region are formed on the common substrate by the common fabrication process but have different transition energies.
7. **(Original)** The integrated optical device of claim 6 wherein the difference in transition energies between the core and the active region is a result of selective area epitaxy.
8. **(Original)** The integrated optical device of claim 6 wherein the difference in transition energies between the core and the active region is a result of impurity induced disordering.
9. **(Original)** The integrated optical device of claim 6 wherein the difference in transition energies between the core and the active region is a result of stress-induced disordering.
10. **(Original)** The integrated optical device of claim 1 wherein the optical element includes an active optical device.
11. **(Original)** The integrated optical device of claim 10 wherein:
 the active optical device includes a second semiconductor active region; and

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the second semiconductor active region and the semiconductor active region of the VLSOA are formed on the common substrate by the common fabrication process but have different transition energies.

12. **(Original)** The integrated optical device of claim 11 wherein the difference in transition energies between the two semiconductor active regions is a result of selective area epitaxy.
13. **(Original)** The integrated optical device of claim 11 wherein the difference in transition energies between the two semiconductor active regions is a result of impurity induced disordering.
14. **(Original)** The integrated optical device of claim 11 wherein the difference in transition energies between the two semiconductor active regions is a result of stress-induced disordering.
15. **(Original)** The integrated optical device of claim 1 wherein:
the optical element includes an unguided transparent region positioned to optically couple the semiconductor active region with the unguided transparent region; and the unguided transparent region and the semiconductor active region are formed on the common substrate by the common fabrication process.
16. **(Original)** An integrated optical device comprising:
a vertically lasing semiconductor optical amplifier (VLSOA) comprising:
an amplifier input;
an amplifier output;
a semiconductor active region;
an amplifying path connecting the amplifier input to the amplifier output and traversing the semiconductor active region; and
a vertical laser cavity including the semiconductor active region; and

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an optical element, wherein a portion of the VLSEA and a portion of the optical element are formed on a common substrate by separate fabrication processes.

17. **(Original)** The integrated optical device of claim 16 wherein the portion of the VLSEA and the portion of the optical element are formed by etch and fill.

18. **(Original)** The integrated optical device of claim 16 wherein:
the optical element comprises a passive optical waveguide including a core, the passive optical waveguide positioned to optically couple the passive optical waveguide with the semiconductor active region; and
the semiconductor active region and the core are formed on the common substrate by the separate fabrication processes.

19. **(Original)** The integrated optical device of claim 16 wherein:
the optical element includes an active optical element having a second semiconductor active region positioned to optically couple the semiconductor active region of the VLSEA with the second semiconductor active region of the active optical element; and
the semiconductor active region of the VLSEA and the second semiconductor active region are formed on the common substrate by the separate fabrication processes.

20. **(Original)** An integrated optical device comprising:
a vertically lasing semiconductor optical amplifier (VLSEA) comprising:
an amplifier input;
an amplifier output;
a semiconductor active region;
an amplifying path connecting the amplifier input to the amplifier output and traversing the semiconductor active region; and
a vertical laser cavity including the semiconductor active region; and
an optical element, wherein the VLSEA and the optical element are formed on separate substrates by separate fabrication processes and integrated onto a common substrate.

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21. **(Original)** The integrated optical device of claim 20 wherein the optical element includes a passive optical waveguide positioned to optically couple the passive optical waveguide with the semiconductor active region.
22. **(Original)** The integrated optical device of claim 20 wherein the optical element includes an active optical element having a second semiconductor active region positioned to optically couple the semiconductor active region of the VLSEA with the second semiconductor active region of the active optical element.
23. **(Cancelled)**
24. **(Currently Amended)** A method for making an integrated optical device comprising:
forming a vertically lasing semiconductor optical amplifier (VLSEA) on a substrate;
forming an optical element on the substrate;
~~The method of claims 23 wherein:~~
wherein the steps of forming a VLSEA and forming an optical element comprise using a common fabrication process; and
at least one parameter varies between the VLSEA and the optical element.
25. **(Original)** The method of claim 24 wherein the step of using a common fabrication process comprises:
placing a selective area epitaxy mask over selected areas of the substrate; and depositing material on the masked substrate, whereby the selective area epitaxy mask results in a difference between a transition energy of the material deposited on a first unmasked area of the substrate and a transition energy of the material deposited on a second unmasked area of the substrate, the VLSEA comprising the material deposited on the first unmasked area of the substrate and the optical element comprising the material deposited on the second unmasked area of the substrate.

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26. **(Original)** The method of claim 25 wherein the selective area epitaxy mask results in a difference between a composition of the material deposited on the first unmasked area of the substrate and a composition of the material deposited on the second unmasked area of the substrate.

27. **(Original)** The method of claim 24 wherein the step of using a common fabrication process comprises:
placing an impurity induced disordering mask over selected areas of the substrate; and
bombarding the masked substrate with impurities, whereby the impurity induced disordering mask results in a difference between a transition energy of the material underlying a masked area of the substrate and a transition energy of the material underlying an unmasked area of the substrate, the VLSEA comprising the material underlying the masked area of the substrate and the optical element comprising the material underlying the unmasked area of the substrate.

28. **(Original)** The method of claim 24 wherein the step of using a common fabrication process comprises:
placing an impurity induced disordering mask over selected areas of the substrate; and
bombarding the masked substrate with impurities, whereby the impurity induced disordering mask results in a difference between a transition energy of the material underlying a masked area of the substrate and a transition energy of the material underlying an unmasked area of the substrate, the VLSEA comprising the material underlying the unmasked area of the substrate and the optical element comprising the material underlying the masked area of the substrate.

29. **(Original)** The method of claim 24 wherein the step of using a common fabrication process comprises:
using stress-induced disordering to cause a difference between a transition energy of a portion of the VLSEA and a portion of the optical element.

30. **(Currently Amended)** The method of claim ~~23~~ 24 wherein:
the step of forming a VLSEA on the substrate comprises depositing a first material on the substrate; and

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the step of forming an optical element on the substrate comprises:
removing the first material from selected areas of the substrate; and
depositing a second material on the selected areas.

31. **(Currently Amended)** The method of claim ~~23~~ 24 wherein:
the step of forming an optical element on the substrate comprises depositing a first material on the substrate; and
the step of forming a VLSEA on the substrate comprises:
removing the first material from selected areas of the substrate; and
depositing a second material on the selected areas.
32. **(Original)** A method for making an integrated optical device comprising:
forming a vertically lasing semiconductor optical amplifier (VLSEA) on a first substrate;
forming an optical element on a second substrate; and
integrating the VLSEA and the optical element onto a common substrate.
33. **(Original)** The method of claim 32 wherein the step of integrating the VLSEA and the optical element onto a common substrate comprises one step selected from the group consisting of:
integrating the VLSEA onto the second substrate; and
integrating the optical element onto the first substrate.
34. **(Original)** The method of claim 33 wherein:
the step of forming an optical element on a second substrate comprises forming a passive optical waveguide on the second substrate; and
the step of integrating the VLSEA and the optical element onto a common substrate comprises:
generating in the second substrate a depression for the VLSEA;
positioning the VLSEA within the depression to optically couple the VLSEA to the transparent optical waveguide; and
fixing the VLSEA within the depression.